



BSI Standards Publication

Thermal-links — Requirements and application guide

National foreword

This British Standard is the UK implementation of EN IEC 60691:2023+A1:2024. It is identical to IEC 60691:2023, incorporating amendment 1:2024. It supersedes BS EN IEC 60691:2023, which will be withdrawn on 31 December 2027.

The start and finish of text introduced or altered by amendment is indicated in the text by tags. Tags indicating changes to IEC text carry the number of the IEC amendment. For example, text altered by IEC amendment 1 is indicated by A1 A1.

The UK participation in its preparation was entrusted to Technical Committee PEL/32, Fuses.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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English Version

Thermal-links - Requirements and application guide (IEC 60691:2023)

Protecteurs thermiques - Exigences et guide d'application
(IEC 60691:2023)

Temperatursicherungen - Anforderungen und
Anwendungshinweise
(IEC 60691:2023)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

The text of document 32C/604/FDIS, future edition 5 of IEC 60691, prepared by SC 32C "Miniature fuses" of IEC/TC 32 "Fuses" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60691:2023.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2024-07-04 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2026-10-04 document have to be withdrawn

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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 60085:2007	NOTE Approved as EN 60085:2008 (not modified)
IEC 60695-10-3:2016	NOTE Approved as EN 60695-10-3:2016 (not modified)
IEC 60695-11-20:2015	NOTE Approved as EN 60695-11-20:2015 (not modified)
IEC 60127-1:2006	NOTE Approved as EN 60127-1:2006 (not modified)
IEC 60127-1:2006/A1:2011	NOTE Approved as EN 60127-1:2006/A1:2011 (not modified)
IEC 60127-1:2006/A2:2015	NOTE Approved as EN 60127-1:2006/A2:2015 (not modified)
IEC 60216-1:2013	NOTE Approved as EN 60216-1:2013 (not modified)
IEC 60695-2-11:2021	NOTE Approved as EN IEC 60695-2-11:2021 (not modified)

European foreword to Amendment 1

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60065	2014	Audio, video and similar electronic apparatus - Safety requirements	-	-
IEC 60112	2020	Method for the determination of the proof and the comparative tracking indices of solid insulating materials	EN IEC 60112	2020
IEC 60127-2	2014	Miniature fuses - Part 2: Cartridge fuse-links	EN 60127-2	2014
IEC 60216-5	2008	Electrical insulating materials - Thermal endurance properties - Part 5: Determination of relative thermal endurance index (RTE) of an insulating material	EN 60216-5	2008
IEC 60664-1	2020	Insulation coordination for equipment within low-voltage supply systems - Part 1: Principles, requirements and tests	EN IEC 60664-1	2020
IEC 60695-2-12	2021	Fire hazard testing - Part 2-12: Glowing/hot-wire based test methods - Glow-wire flammability index (GWFI) test method for materials	EN IEC 60695-2-12	2021
IEC 60695-2-13	2021	Fire hazard testing - Part 2-13: Glowing/hot-wire based test methods - Glow-wire ignition temperature (GWIT) test method for materials	EN IEC 60695-2-13	2021
IEC 60695-10-2	2014	Fire hazard testing - Part 10-2: Abnormal heat - Ball pressure test method	EN 60695-10-2	2014
IEC 60695-11-10	2013	Fire hazard testing - Part 11-10: Test flames - 50 W horizontal and vertical flame test methods	EN 60695-11-10	2013
IEC 60730-1 (mod)	2013	Automatic electrical controls - Part 1: General requirements	EN 60730-1	2016
+ A1	2015		+ A1	2019
+ A2	2020		+ A2	2022

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61210 (mod)	2010	Connecting devices - Flat quick-connect terminations for electrical copper conductors - Safety requirements	EN 61210	2010

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

THERMAL-LINKS – REQUIREMENTS AND APPLICATION GUIDE

FOREWORD

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IEC 60691 has been prepared by subcommittee 32C: Miniature fuses, of IEC technical committee 32: Fuses. It is an International Standard.

This fifth edition cancels and replaces the fourth edition published in 2015 and Amendment 1:2019. This edition constitutes a technical revision.

This fifth edition includes the following significant technical changes with respect to the previous edition:

- a) requirements for thermal-link packaged assemblies;
- b) renew the requirements and definitions for T_h -test;

The harmonization of the USA national standard, UL 1020, fifth edition (withdrawn 2003), and IEC 60691:1993, together with its Amendment 1:1995 and Amendment 2:2000 have served as a basis for the elaboration of this standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
32C/604/FDIS	32C/605/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

The following differing practices of a less permanent nature exist in the country indicated below:

- Annex C is required to be declared in the USA;
- Annex E is required in the USA, if applicable;
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- *compliance statements: in italic type.*

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

Thermal-links, defined as non-resettable devices functioning once only without refunctioning, are widely applied for the thermal protection of equipment in which, under fault (abnormal) conditions, one or more parts may reach hazardous temperatures.

As these devices have several aspects in common with miniature fuse-links and are used for obtaining a comparable degree of protection, this standard has endeavoured to lay down a number of basic requirements for such devices.

THERMAL-LINKS – REQUIREMENTS AND APPLICATION GUIDE

1 Scope

This International Standard is applicable to thermal-links intended for incorporation in electrical appliances, electronic equipment and component parts thereof, normally intended for use indoors, in order to protect them against excessive temperatures under abnormal conditions.

NOTE 1 The equipment is not designed to generate heat.

NOTE 2 The effectiveness of the protection against excessive temperatures logically depends upon the position and method of mounting of the thermal-link, as well as upon the current which it is carrying.

This document may be applicable to thermal-links for use under conditions other than indoors, provided that the climatic and other circumstances in the immediate surroundings of such thermal-links are comparable with those in this standard.

This document may be applicable to thermal-links in their simplest forms (e.g. melting strips or wires), provided that molten materials expelled during function cannot adversely interfere with the safe use of the equipment, especially in the case of hand-held or portable equipment, irrespective of its position.

Annex H of this document is applicable to thermal-link packaged assemblies where the thermal-link(s) has already been approved to this standard but packaged in a metallic or non-metallic housing and provided with terminals/wiring leads.

This document is applicable to thermal-links with a rated voltage not exceeding 690 V AC or DC and a rated current not exceeding 63 A.

The objectives of this document are:

- a) to establish uniform requirements for thermal-links,
- b) to define methods of test, and
- c) to provide useful information for the application of thermal-links in equipment.

This document is not applicable to thermal-links used under extreme conditions such as corrosive or explosive atmospheres.

This document is not applicable to thermal-links to be used in circuits on AC with a frequency lower than 45 Hz or higher than 62 Hz.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60065:2014, *Audio, video and similar electronic apparatus – Safety requirements*

IEC 60112:2020, *Method for the determination of the proof and the comparative tracking indices of solid insulating materials*

IEC 60127-2:2014, *Miniature fuses – Part 2: Cartridge fuse-links*

IEC 60216-5:2008, *Electrical insulating materials – Thermal endurance properties – Part 5: Determination of relative thermal endurance index (RTE) of an insulating material*

IEC 60664-1:2020, *Insulation coordination for equipment within low-voltage supply systems – Part 1: Principles, requirements and tests*

IEC 60695-2-12:2021, *Fire hazard testing – Part 2-12: Glowing/hot-wire based test methods – Glow-wire flammability index (GWFI) test method for materials*

IEC 60695-2-13:2021, *Fire hazard testing – Part 2-13: Glowing/hot-wire based test methods – Glow-wire ignition temperature (GWIT) test method for materials*

IEC 60695-10-2:2014, *Fire hazard testing – Part 10-2: Abnormal heat – Ball pressure test method*

IEC 60695-11-10:2013, *Fire hazard testing – Part 11-10: Test flames – 50 W horizontal and vertical flame test methods*

IEC 60730-1:2013, *Automatic electrical controls – Part 1: General requirements*
IEC 60730-1:2013/AMD1:2015
IEC 60730-1:2013/AMD2:2020

IEC 61210:2010, *Connecting devices – Flat quick-connect terminations for electrical copper conductors – Safety requirements*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

clearance

shortest distance in air between two conductive parts

3.2

creepage distance

shortest distance along the surface of insulating material between two conductive parts

3.3

holding temperature

T_h

maximum ambient temperature of the thermal-link at which it will not change its state of conductivity during a specified time at a specified rated current

3.4**homogeneous series**

series of thermal-links having the same external dimensions and common overall construction, deviating from each other only in such characteristics (including ratings) that, for a given test, the testing of one or a reduced number of particular thermal-links of that series shall be taken as representative for all the thermal-links of the series

3.5**interrupting current** I_b

value of the current that the thermal-link is capable of interrupting at rated voltage and under specified circuit conditions

3.6**maximum temperature limit** T_m

temperature of the thermal-link stated by the manufacturer, up to which the mechanical and electrical properties of the thermal-link, having changed its state of conductivity, will not be impaired for a given time

3.7**pilot duty**

rating assigned to a switching device that controls the coil of another electro-mechanical device such as a solenoid, relay or contactor

3.8**portable equipment**

equipment which is moved while in operation or which can easily be moved from one place to another while connected to the supply

3.9**rated current** I_r

current used to classify a thermal-link

3.10**rated functioning temperature** T_f

temperature of the thermal-link which causes it to change its state of conductivity with a detection current up to 10 mA as the only load

3.11**rated voltage** U_r

voltage used to classify a thermal-link

3.12**thermal element**

metallic or non-metallic fusible material that is part of a thermal-link and is responsive to temperature by a change of state such as from solid to liquid at the temperature for which it is calibrated

3.13**thermal-link**

non-resettable device incorporating a thermal element, which will open a circuit once only when exposed for a sufficient length of time to a temperature in excess of that for which it has been designed

3.14

transient overload current

I_p

direct current pulse train which the thermal-link is able to withstand without impairing its characteristics

3.15

extended holding temperature

T_{h-100}

maximum temperature at which a thermal-link can be maintained while conducting the rated current at the rated voltage for a period of 100 weeks which will not cause the thermal-link to open circuit in accordance with extended holding temperature evaluation

Note 1 to entry: This is a rating for user consideration during the investigation of the end product.

Note 2 to entry: Annex D specifies the extended holding temperature evaluation.

3.16

conductive heat ageing test

CHAT

test to evaluate a thermal-link for use in an appliance

Note 1 to entry: If it performs satisfactorily, the thermal-link will be assigned a CHAT rating. This rating is for end-product user consideration during the investigation of the end-use product.

Note 2 to entry: Annex C specifies the conductive heat ageing test.

4 General requirements

4.1 Adequate protection of the equipment against excessive temperatures not only depends upon the properties of the thermal-link but also to a large extent upon the mounting of the thermal-link in the equipment. Therefore the requirements of the application guide in Annex A shall be considered.

4.2 Thermal-links shall have adequate electrical and mechanical strength and shall be constructed so as to withstand all conditions of handling likely to be encountered during mounting and normal use, when used within the requirements of this document.

4.3 When a thermal-link changes its state of conductivity, no arc or flame shall be maintained, nor material expelled, that might impair the surrounding area or otherwise create a risk of electric shock or fire. In addition, there shall be no emission of substances (e.g. gases, liquids, dust, mist, vapour) which could cause a hazard.

For thermal-links using melting strips or wires, care should be taken to prevent molten material from short-circuiting or bridging creepage distances and clearances in air, so as to reduce the risk of impairing the insulation system of the equipment.

After it has functioned, the thermal-link shall not be damaged when subjected to temperatures not exceeding T_m , in such a way that the safety of the equipment with regard to risk of electric shock hazard and electrical breakdown is impaired. The thermal-link shall not reclose after it has operated.

4.4 For requirements for thermal-link packaged assemblies, see Annex H.